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**Različica specifikacije Qi 2.0 - 10. del: Specifikacija sistema Mpp (IEC 63563-10:2025)**

Qi specification version 2.0 - Part 10: Mpp system specification (IEC 63563-10:2025)

Qi Spezifikation Version 2.0 - Teil 10: Mpp System Spezifikation (IEC 63563-10:2025)

Spécification Qi version 2.0 - Partie 10: Spécification du système PPM (Profil de puissance magnétique) (IEC 63563-10:2025)

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(IEC 63563-10:2025)**

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(IEC 63563-10:2025)

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## EN IEC 63563-10:2025 (E)

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The text of document 100/4254/FDIS, future edition 1 of IEC 63563-10, prepared by TC 100/Technical Area 15 "Wireless Power Transfer" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 63563-10:2025.

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IEC 63563-10

Edition 1.0 2025-02

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It is based on *Qi Specification version 2.0, MPP System Specification* and was submitted as a Fast-Track document.

The text of this International Standard is based on the following documents:

Draft	Report on voting
100/4254/FDIS	100/4275/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

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## Qi Specification

### *MPP System Specification*

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**Version 2.0**

**April 2023**

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## RELEASE HISTORY

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2.0	April 2023	First release of this v2.0 specification.

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